

RSSKRX23E-B

Renesas Solution Starter Kit for RX23E-B

1. Overview

Renesas Solution Starter Kit for RX23E-B (hereafter, referred to as RSSKRX23E-B) is an evaluation board for sensor measurement equipped with RX23E-B. By using QE for AFE which is provided separately, it is possible to perform operation setting for RX23E-B and acquire A/D conversion values. In addition, it is available for operation of the sample code using this board and program development.

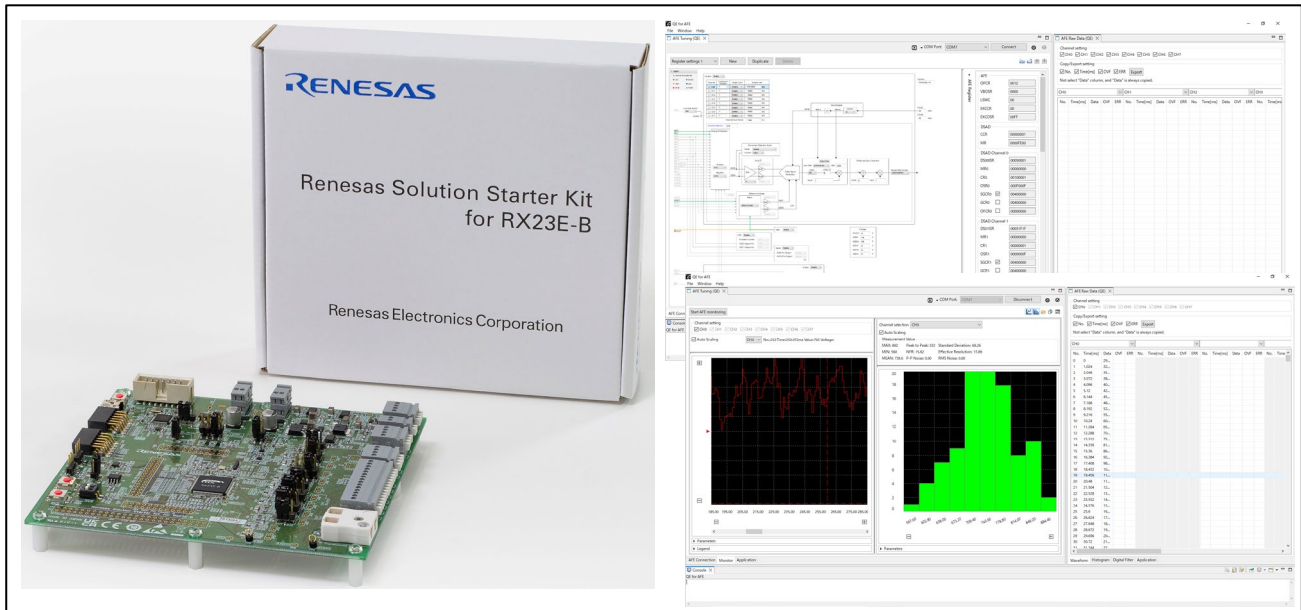


Figure 1-1 Renesas Solution Starter Kit for RX23E-B and QE for AFE

2. Offering Items

The following items are downloadable from Renesas Electronics web site.

- Related to RSSKRX23E-B (RTK0ES1001C00001BJ)
 - R20UZ4108 RSSKRX23E-B User's Manual
 - R20QS0044 Quick Start Guide RSSKRX23E-B Renesas Solution Starter Kit for RX23E-B (this document)
 - R01AN6364 RX23E-B Group “RSSKRX23E-B Board Control Program” (Including RX23E-B program binary file written at the shipment of the board)
- Tools
 - Renesas QE for AFE (V2.3.1 or later)
 - Renesas Flash Programmer (V3.12.00 or later)
- Examples of use
 - Example of load cell measurement: R01AN6512 Application Note “Design and weight measurement of tiny board for digital load cell”
 - Example of temperature or voltage measurement: R01AN6518 Application Note “Example of 4-20mA transmitter using built-in D/A converter”
- Related documents
 - R01AN6517 Application Note “Example of weight measurement using AC excited load cell”
 - R01AN6513 Application Note “Design and measurement of small board for 6-axis force sensor”

3. Connection and Configuration

This chapter describes from settings for the RSSKRX23E-B board to connection to a PC.

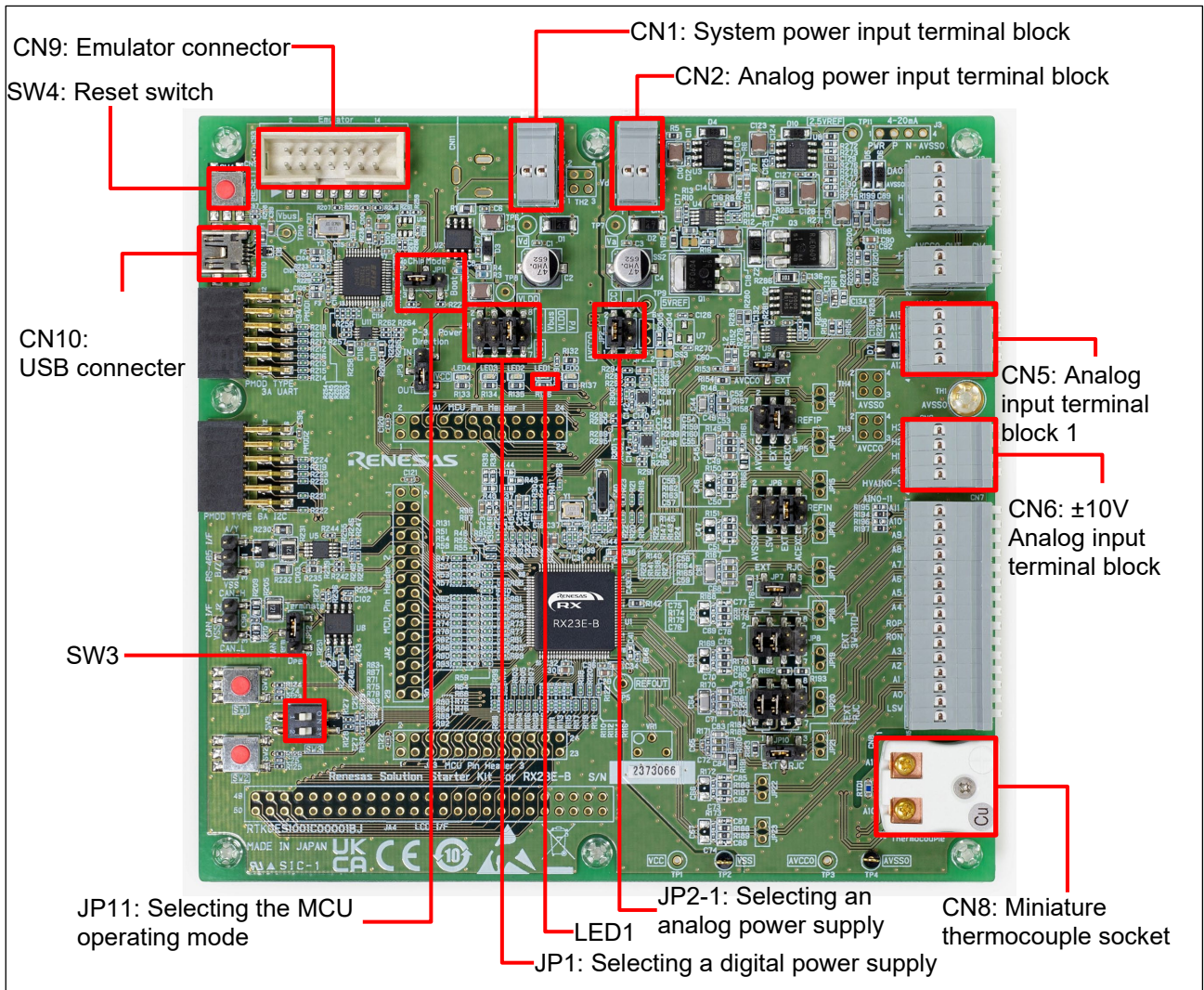


Figure 3-1 Major Connectors and Jumpers on RSSKRX23E-B Board

3.1 Power Supply Configuration

The factory default setting for power supply is system power supply. USB bus power supply is also selectable. Figure 3-2 shows the default setting and USB power supply setting. For details on the power supply configuration, refer to “2.2 Selecting Power Supplies” in RSSKRX23E-B User’s Manual.

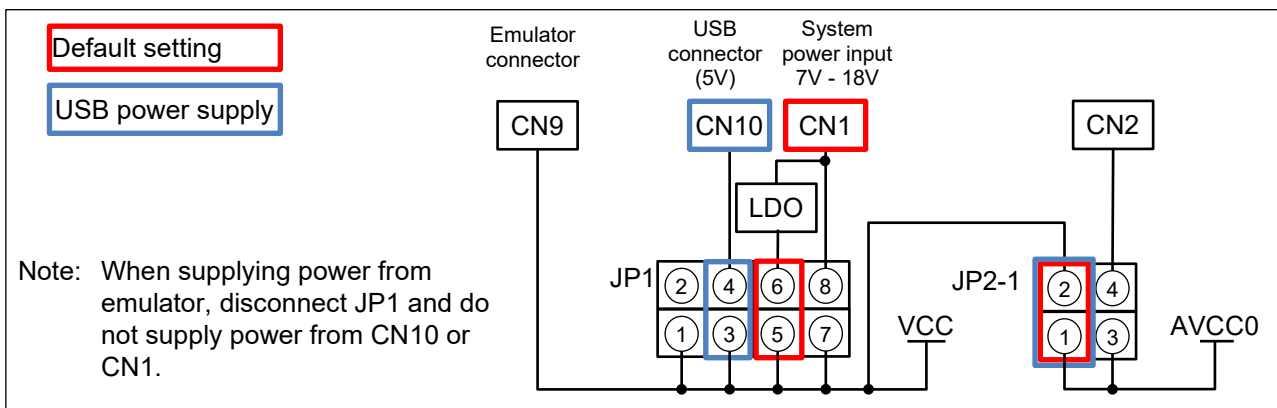


Figure 3-2 Power Supply Configuration

3.2 Connection

Connect CN10 on the board to a PC with a USB cable.

If necessary, it is possible to connect E2/E2 Lite emulator. When using an external power supply or a USB power supply for the system power supply, do not supply power from E2/E2 Lite emulator.

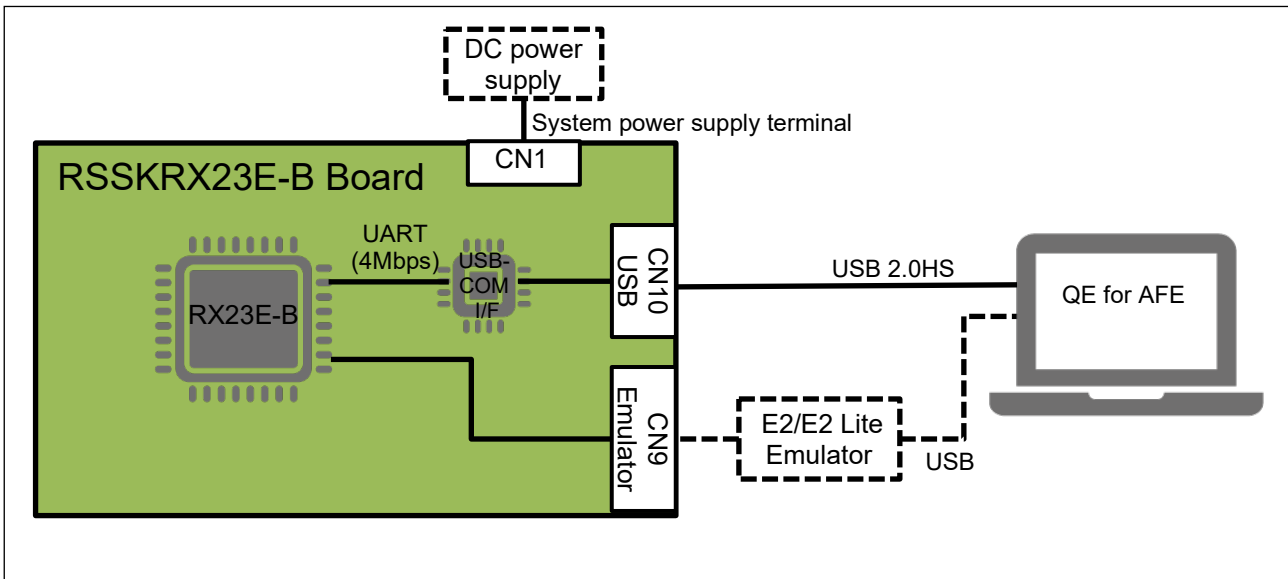


Figure 3-3 Diagram of System Connection

3.3 RX23E-B Board Control Program

The board control program is written into RX23E-B on the RSSKRX23E-B board at the shipment.

If the RX23E-B program has been changed due to software development, execution of the sample program, etc., write “rx23eb_rssk_fw.mot” included in “RSSKRX23E-B Board Control Program”. Renesas Flash Programmer is available for writing, which is downloadable from Renesas Electronics web site. For details, refer to the document of Renesas Flash Programmer.

The followings describe the procedure for writing via CN10: “USB connector” using Renesas Flash Programmer.

1. Stop supplying power to the RSSKRX23E-B board, then set JP11: “Selecting the MCU operating mode” to “Boot” side (1-2).
2. When supplying power from CN1, supply power to the RSSKRX23E-B board, then connect to a PC with a USB cable.
3. Activate Renesas Flash Programmer, configure settings from menu “File” > “Create a new project” referring to Figure 3-4, press the reset switch on the RSSKRX23E-B board, then press “Connect”.
4. Select “rx23eb_rssk_fw.mot” referring to Figure 3-5, press the reset switch on the RSSKRX23E-B board, then press “Start”.
5. After the writing is normally completed, close Renesas Flash Programmer, stop supplying power to the RSSKRX23E-B board, then return JP11 to “Single-Chip” side (2-3).

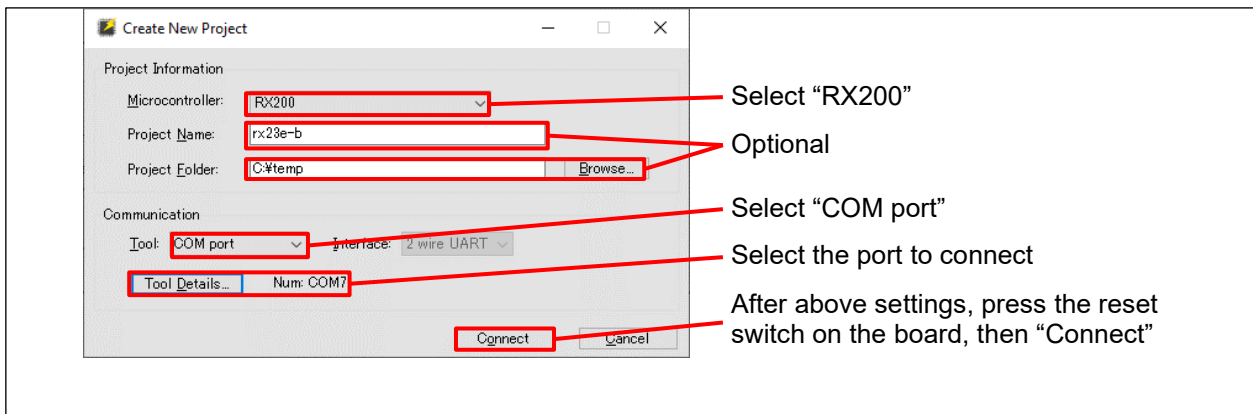


Figure 3-4 Renesas Flash Programmer “Create a New Project”

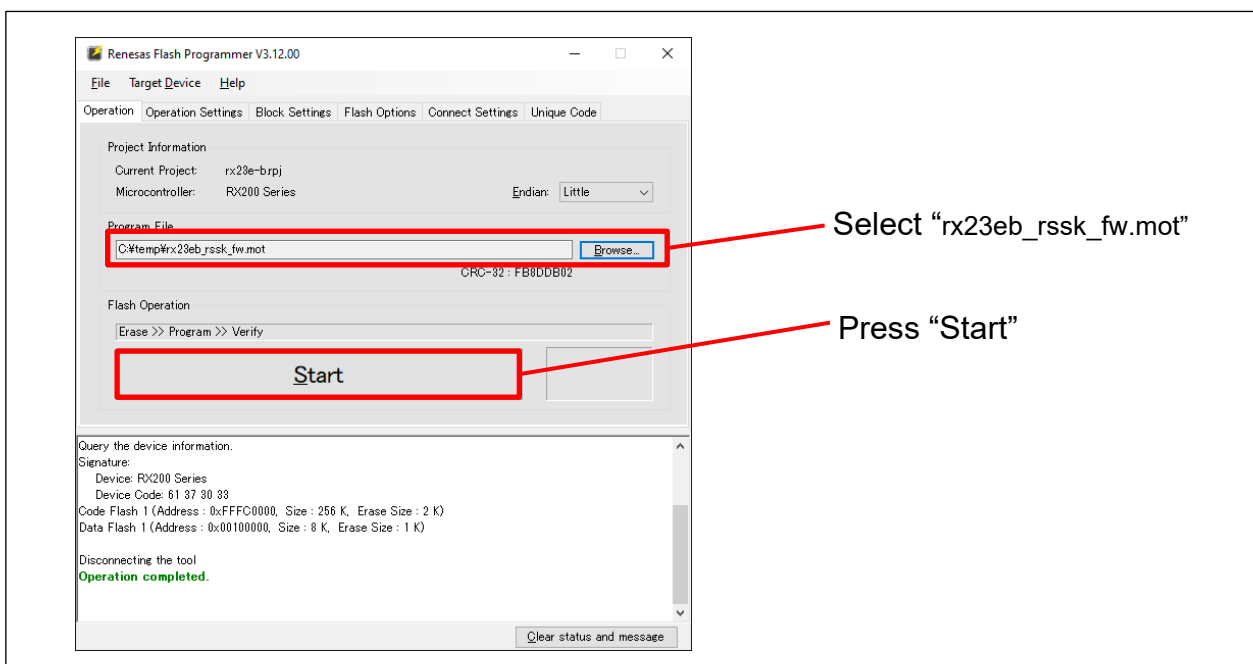


Figure 3-5 Renesas Flash Programmer Writing Operation

4. Example of Use

4.1 AFE, DSAD, and R16DA Evaluation

Since the RSSKRX23E-B board control program is written at the shipment, it is possible to configure settings for AFE, DSAD and R16DA and monitor A/D conversion results by using QE for AFE. If the RX23E-B program has been changed, write the board control program based on “3.3 RX23E-B Board Control Program”

The procedure are described below.

1. Connecting to QE for AFE

Connect the board to a PC, activate QE for AFE, then follow the steps below.

- (1) Select the COM port to connect to the board.
- (2) Set the bit rate to 4,000,000.
- (3) Press the “Connect” button.

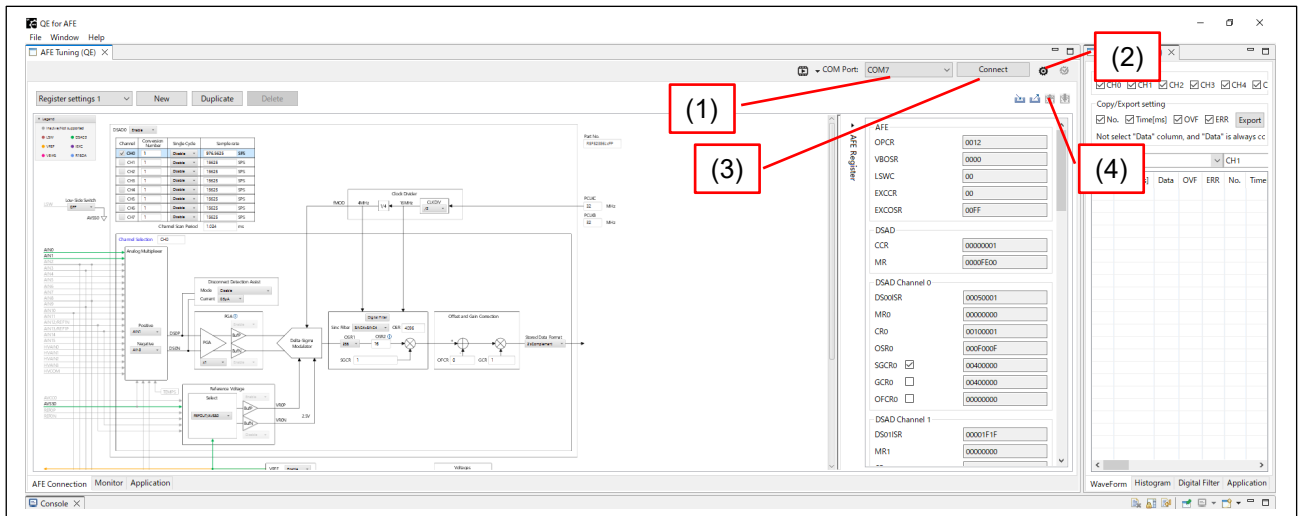


Figure 4-1 QE for AFE Window (Connection and Register Settings)

2. Setting registers

Set the operating conditions for AFE, DSAD, and R16DA on the AFE Connection tab and press (4) “Write Value to the Target Board” button to set them to RX23E-B.

3. Acquiring A/D conversion results

On the Monitor tab shown in Figure 4-2, press the “Start AFE monitoring” button.

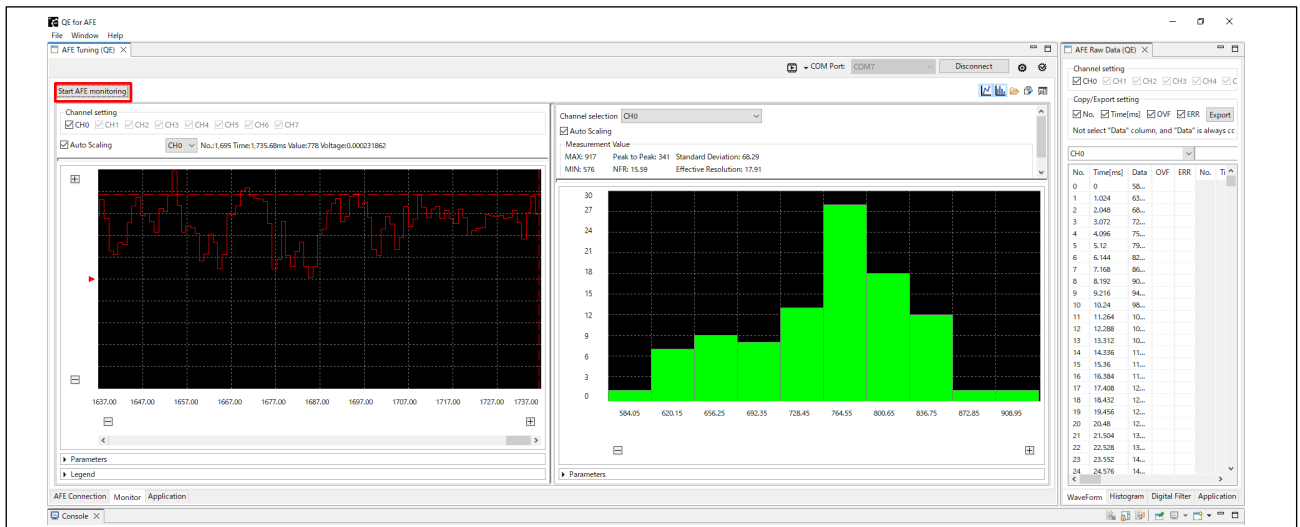


Figure 4-2 QE for AFE Window (Monitor Tab)

4.2 Temperature and Voltage Measurement

By using the RX23E-B program “rx23eb_4_20ma.mot” included in the Application Note “4-20mA transmitter using built-in D/A converter” sample program, measurement results of temperature or voltage can be monitored on the Application tab of QE for AFE. For details, refer to the Application Note.

1. Writing the program

Write “rx23eb_4_20ma.mot” by following the procedures in “3.3 RX23E-B Board Control Program”.

2. Preparing the measurement target

As shown in Table 4-1, connect and configure settings according to the measurement target.

Table 4-1 Measurement Target and Connection/Settings

Measurement target	Connection	SW3-1 Settings
Temperature	Connect a thermocouple Type-K to CN8	OFF
Voltage	Input voltage to CN6 + side: CN6-1 (HVAIN3) - side: CN6-2 (HVAIN2)	ON

3. Connecting to QE for AFE

Connect the board to a PC, activate QE for AFE, then follow the steps below as shown in Figure 4-1.

- (1) Select the COM port to connect to the board.
- (2) Set the bit rate to 4,000,000.
- (3) Press the “Connect” button.

4. Acquiring measurement results

On the Application tab shown in Figure 4-3, press (1) “Start Application monitoring” to acquire the measurement result. The measurement result is displayed with CH0.

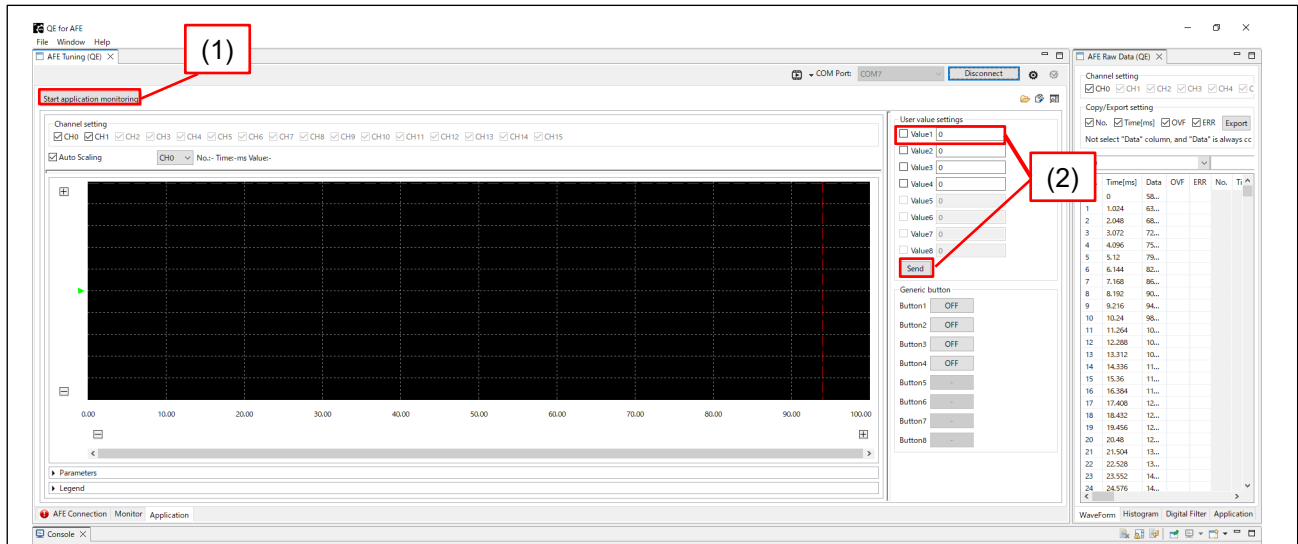


Figure 4-3 QE for AFE Window (Application Tab)

4.3 Example of Weight Measurement with Load Cell

By using the RX23E-B program “rx23eb_loadcell_qe_rssk.mot” included in the Application Note “Design and weight measurement of tiny board for digital load cell” sample code, results of measuring weight with load cell can be monitored. For details, refer to the Application Note.

1. Writing the program

Write “rx23eb_loadcell_qe_rssk.mot” by following the procedures in “3.3 RX23E-B Board Control Program.”

2. Preparing the measurement target and Connecting

Connect a prepared load cell as shown in Table 4-2. For details, refer to “RSSKRX23E-B User’s Manual 2.4.6 Load Cell Measurement Circuit”.

Table 4-2 Load Cell Connection/Settings

Item	Connection/Setting
Load cell positive input (power supply +)	CN5-3: AIN13/REF1P
Load cell negative input (power supply -)	CN5-4: AIN12/REF1N
Load cell positive output	CN5-1: AIN15
Load cell negative output	CN5-2: AIN14
JP5	1-2
JP6	1-2

3. Connecting to QE for AFE

Connect the board to a PC, activate QE for AFE, then follow the steps below as shown in Figure 4-1.

- (1) Select the COM port to connect to the board.
- (2) Set the bit rate to 1,000,000.
- (3) Press the “Connect” button.

4. Calibration

To adjust the weight conversion coefficient to the load cell to be used, perform calibration. Follow the calibration procedure below on the Application tab as shown in Figure 4-3. For details, refer to Table 1-1 and “6.3 Calibration” in the Application Note.

- 1) Put Weight 1 on the load cell.
- 2) For Value 1 of (2) User value setting in Figure 4-3,
 - Check the checkbox.
 - Enter the weight of Weight 1.
 - Press “Send”.
- 3) When LED1 is blinking on the board, put Weight 2 on the load cell.

For Value 2 of (2) User value setting in figure 4-3,

 - Check the checkbox.
 - Enter the weight of Weight 2.
 - Press “Send”.
- 4) If LED1 turns on, the calibration is normally completed. If it blinks five times and then turns off, the calibration is failed.

5. Acquiring measurement results

On the Application tab shown in Figure 4-3, press “Start Application monitoring” to acquire the measurement result. The measurement result is displayed with CH0.

Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Oct.30.23	-	First release.

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity.

Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

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